

HAT2207C

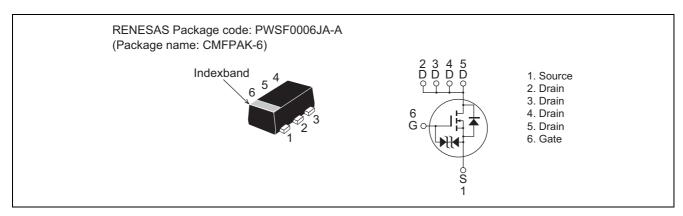
Silicon N Channel MOS FET Power Switching

REJ03G1239-0600 Rev.6.00 Feb 28, 2006

Features

- Low on-resistance $R_{DS(on)} = 100 \ m\Omega \ typ. \ (at \ V_{GS} = 4.5 \ V)$
- Low drive current.
- High density mounting
- 2.5 V gate drive devices.

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	20	V	
Gate to source voltage	V_{GSS}	±12	V	
Drain current	I _D	1.5	А	
Drain peak current	I _D (pulse) ^{Note1}	6	А	
Body - Drain diode reverse drain current	I _{DR}	1.5	А	
Channel dissipation	Pch ^{Note 2}	790	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. When using the glass epoxy board. (FR4 40 \times 40 \times 1.6 mm)

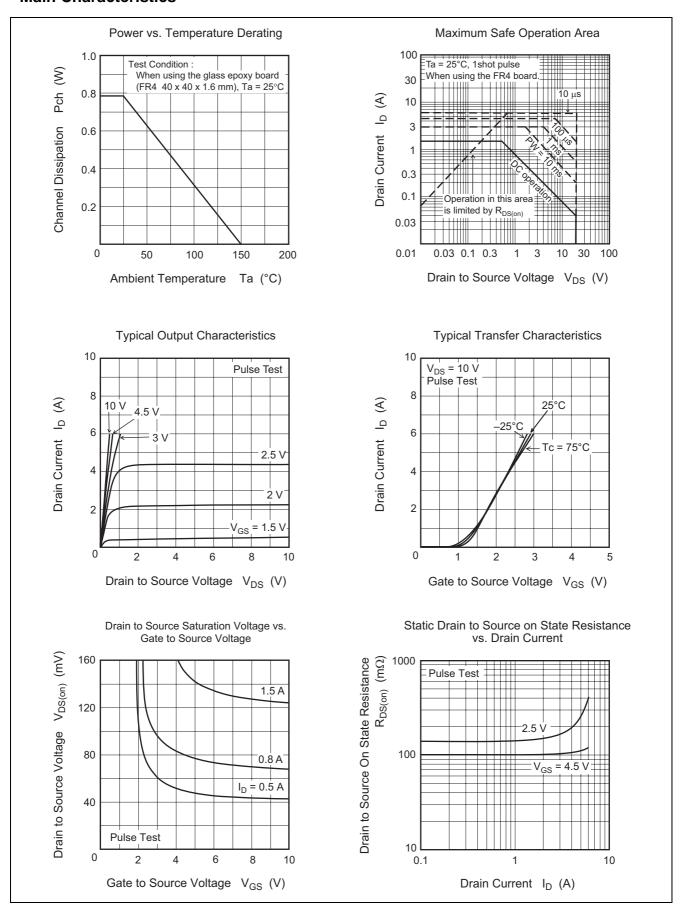
Electrical Characteristics

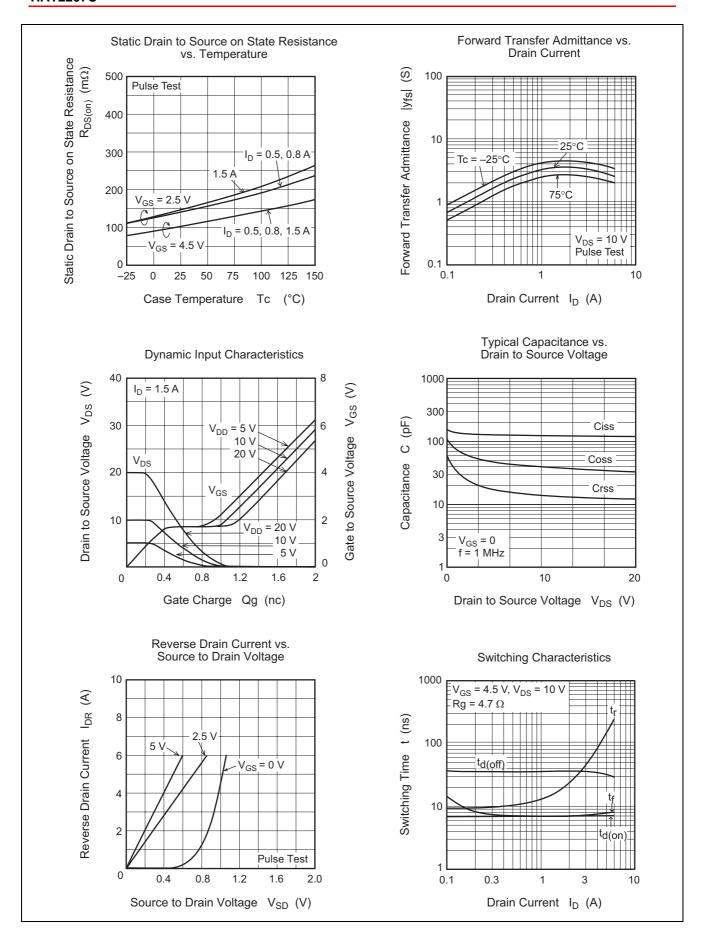
 $(Ta = 25^{\circ}C)$

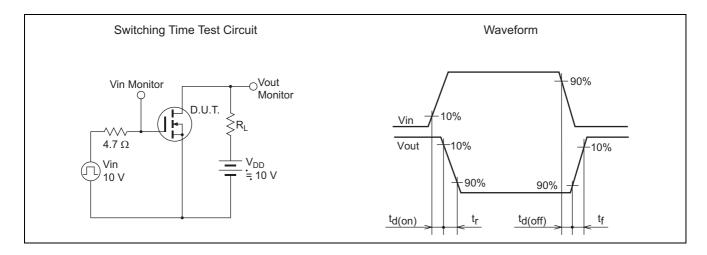
Item	Symbol	Min.	Тур.	Max.	Unit	Test Conditions
Drain to Source breakdown voltage	$V_{(BR)DSS}$	20	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to Source breakdown voltage	$V_{(BR)GSS}$	±12	_	_	V	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0$
Gate to Source leakage current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$
Drain to Source leakage current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 20 \text{ V}, V_{GS} = 0$
Gate to Source cutoff voltage	$V_{GS(off)}$	0.4	_	1.4	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}^{\text{Note3}}$
Drain to Source on state resistance	R _{DS(on)}	_	100	130	mΩ	$I_D = 0.8 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note3}}$
		_	140	210	mΩ	$I_D = 0.8 \text{ A}, V_{GS} = 2.5 \text{ V}^{\text{Note3}}$
Forward transfer admittance	y _{fs}	1.5	3	_	S	$I_D = 0.8 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss	_	135	_	pF	$V_{GS} = 0$, $f = 1$ MHz,
Output capacitance	Coss	_	40	_	pF	V _{DS} = 10 V
Reverse transfer capacitance	Crss	_	15	_	pF	
Total gate charge	Qg	_	1.7	_	nC	V _{GS} = 4.5 V, V _{DS} = 10 V,
Gate to Source charge	Qgs	_	0.4	_	nC	I _D = 1.5 A
Gate to Drain charge	Qgd	_	0.5	_	nC	
Turn - on delay time	t _{d(on)}	_	7	_	ns	$V_{GS} = 10 \text{ V}, I_D = 0.8 \text{ A},$
Rise time	t _r	_	11	_	ns	$V_{DD} = 10 \text{ V}, R_L = 12.5 \Omega,$
Turn - off delay time	t _{d(off)}	_	35	_	ns	$R_g = 4.7 \Omega$
Fall time	t _f	_	7	_	ns	
Body - Drain diode forward voltage	V_{DF}	_	0.85	1.1	V	I _F = 1.5 A, V _{GS} = 0

Notes: 3. Pulse test

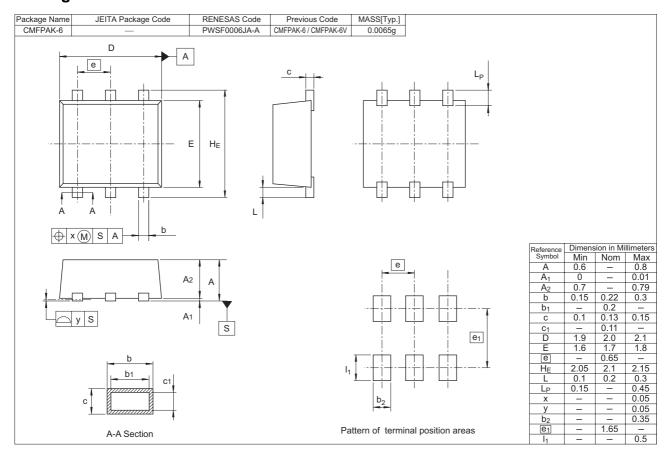
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2207C-EL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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